TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

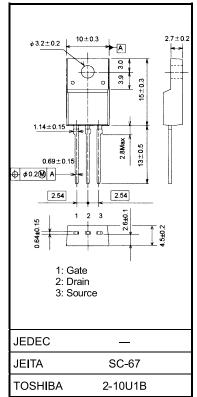
2SK3562

Switching Regulator Applications

- Low drain-source ON resistance: $RDS(ON) = 0.9 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 5.0S$ (typ.)
- Low leakage current: $IDSS = 100 \ \mu A (VDS = 600 V)$
- Enhancement mode: $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ID} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	600	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	600	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	6		
	Pulse (t = 1 ms) (Note 1)	I _{DP}	24	A	
Drain power dissipati	on (Tc = 25°C)	PD	40	W	
Single pulse avalanche energy (Note 2)		E _{AS}	345	mJ	
Avalanche current		I _{AR}	6	А	
Repetitive avalanche energy (Note 3)		E _{AR}	4	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.7 g (typ.)

Thermal Characteristics

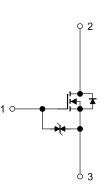
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD} = 90 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}(\text{initial}), \text{ L} = 16.8 \text{ mH}, \text{ I}_{AR} = 6 \text{ A}, \text{ R}_{G} = 25 \Omega$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.



Unit: mm

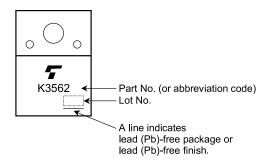
Electrical Characteristics (Ta = 25°C)

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		GSS	$V_{GS}=\pm 25~V,~V_{DS}=0~V$	_	_	±10	μA
Gate-source brea	akdown voltage	V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30	_	_	V
Drain cut-off curr	ent	I _{DSS}	$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		_	100	μA
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	600	_		V
Gate threshold ve	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0	_	4.0	V
Drain-source ON	resistance	R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}$		0.9	1.25	Ω
Forward transfer	ard transfer admittance $ Y_{fs} $ $V_{DS} = 10 \text{ V}, I_D = 3 \text{ A}$		$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}$	1.2	5.0		S
Input capacitance		C _{iss}			1050		pF
Reverse transfer capacitance		C _{rss}	$V_{DS} = 25 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$	_	10		
Output capacitance		C _{oss}		_	110		
Switching time	Rise time	tr	V_{GS} 0 V 0 V	_	20		ns
	Turn-on time	t _{on}			40	_	
	Fall time	t _f			35	_	
	Turn-off time	t _{off}	Duty \leq 1%, t _w = 10 μ s		130		
Total gate charge		Qg			28	_	
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 6 \text{ A}$		16	_	nC
Gate-drain charge		Q _{gd}	1	—	12	_	

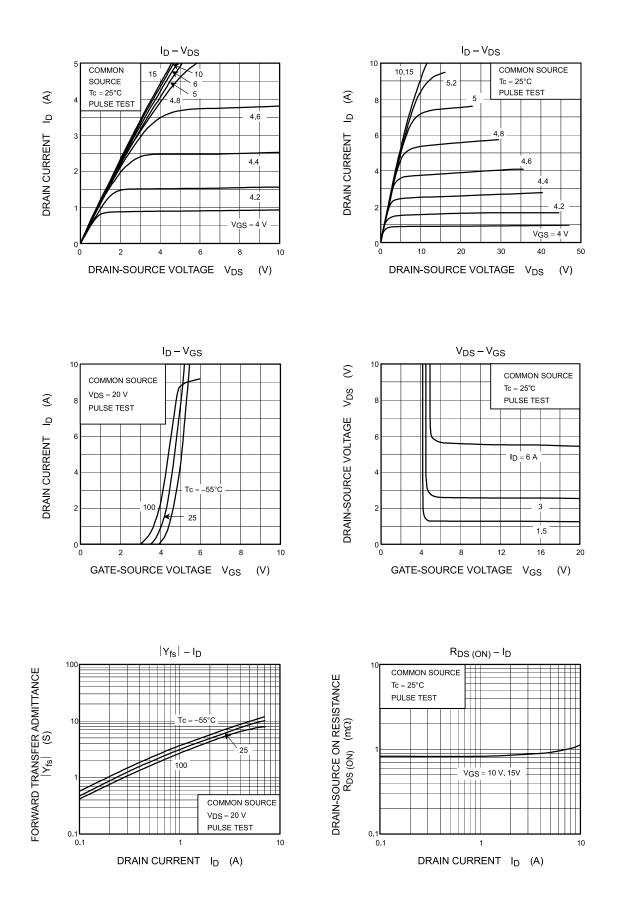
Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	6	А
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	24	А
Forward voltage (diode)	V _{DSF}	$I_{DR} = 6 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V},$	_	1000	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 100 A/μs	_	7.0	_	μC

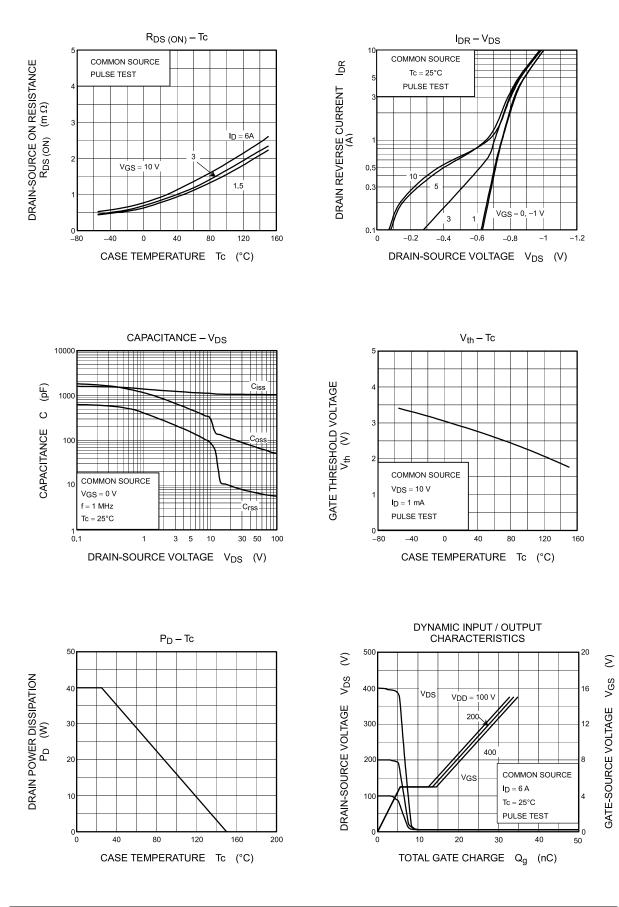
Marking

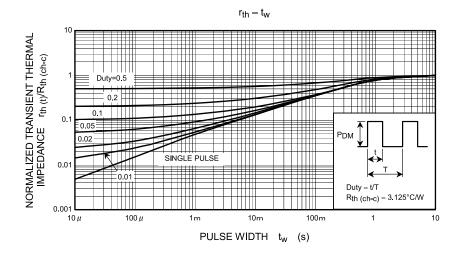


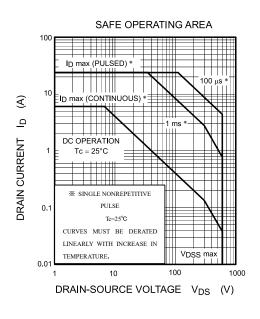
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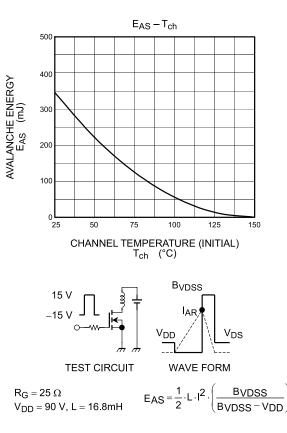


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